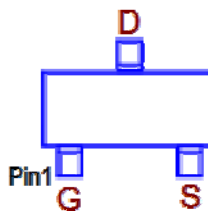
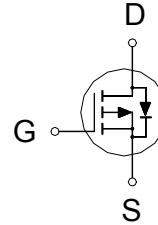




**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
-30V	48mΩ	-3.3A



G: GATE  
D: DRAIN  
S: SOURCE

**Features**

- Pb-Free, Halogen Free and RoHS compliant.
- Low  $R_{DS(on)}$  to Minimize Conduction Losses.
- Ohmic Region Good  $R_{DS(on)}$  Ratio.
- Optimized Gate Charge to Minimize Switching Losses.

**Applications**

- Protection Circuits Applications.
- Logic/Load Switch Circuits Applications.

**ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ °C}$  Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		$V_{GS}$	±12	V
Continuous Drain Current	$T_A = 25\text{ °C}$	$I_D$	-3.3	A
	$T_A = 70\text{ °C}$		-2.6	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	-16	
Power Dissipation	$T_A = 25\text{ °C}$	$P_D$	0.9	W
	$T_A = 70\text{ °C}$		0.6	
Operating Junction & Storage Temperature Range		$T_j, T_{stg}$	-55 to 150	°C

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	$R_{\theta JA}$		130	°C/W

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper.

**ELECTRICAL CHARACTERISTICS ( $T_J = 25\text{ °C}$ , Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.7	-0.9	-1.3	

Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 12V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -24V, V_{GS} = 0V$			-1	$\mu A$
		$V_{DS} = -20V, V_{GS} = 0V, T_J = 55^\circ C$			-10	
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(ON)}$	$V_{GS} = -2.5V, I_D = -1A$		50	75	m $\Omega$
		$V_{GS} = -4.5V, I_D = -3.3A$		40	50	
		$V_{GS} = -10V, I_D = -3.3A$		36	48	
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = -5V, I_D = -3.3A$		15		S

**DYNAMIC**

Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = -15V, f = 1MHz$		807		pF
Output Capacitance	$C_{oss}$			81		
Reverse Transfer Capacitance	$C_{rss}$			61		
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{DS} = -15V, V_{GS} = -4.5V, I_D = -3.3A$		8.6		nC
Gate-Source Charge <sup>2</sup>	$Q_{gs}$			1.1		
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$			2.6		
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$	$V_{DD} = -15V, V_{GS} = -4.5V, I_D \cong -3.3A, R_G = 6\Omega$		19		nS
Rise Time <sup>2</sup>	$t_r$			30		
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$			55		
Fall Time <sup>2</sup>	$t_f$			20		

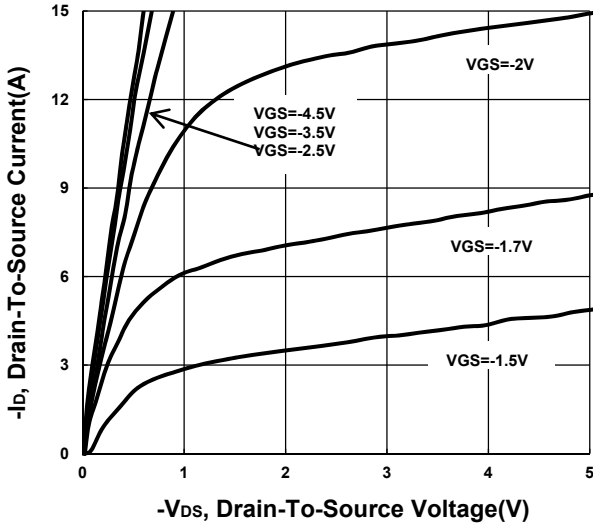
**SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>J</sub> = 25 °C)**

Continuous Current	$I_S$				-0.8	A
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = -3.3A, V_{GS} = 0V$			-1.1	V
Reverse Recovery Time	$t_{rr}$	$I_F = -3.3A, di_F/dt = 100A / \mu S$		8.5		nS
Reverse Recovery Charge	$Q_{rr}$			2.5		nC

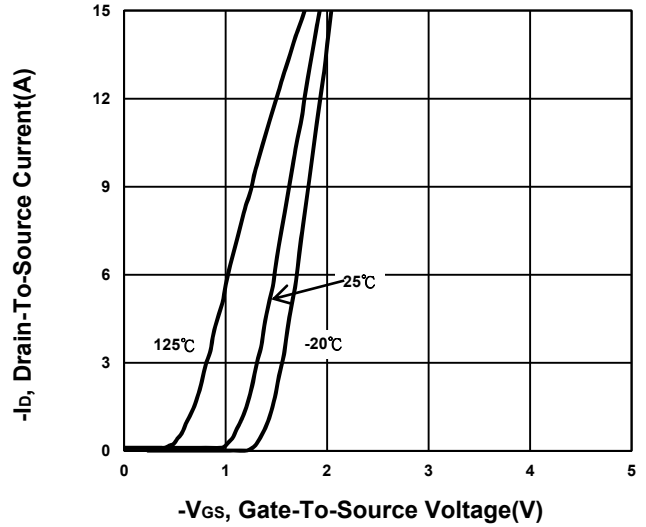
<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu sec$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

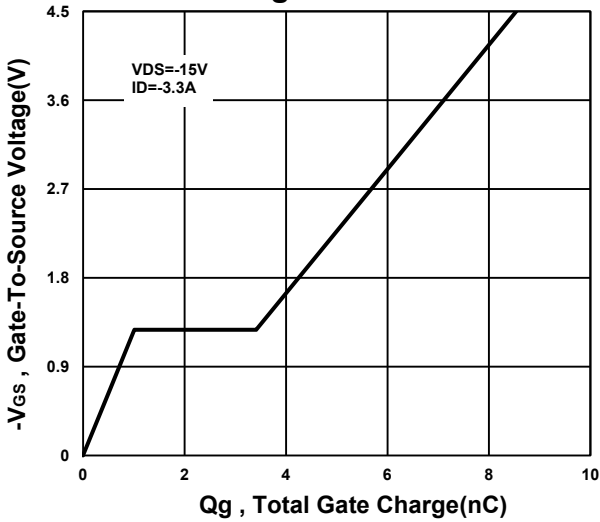
**Output Characteristics**



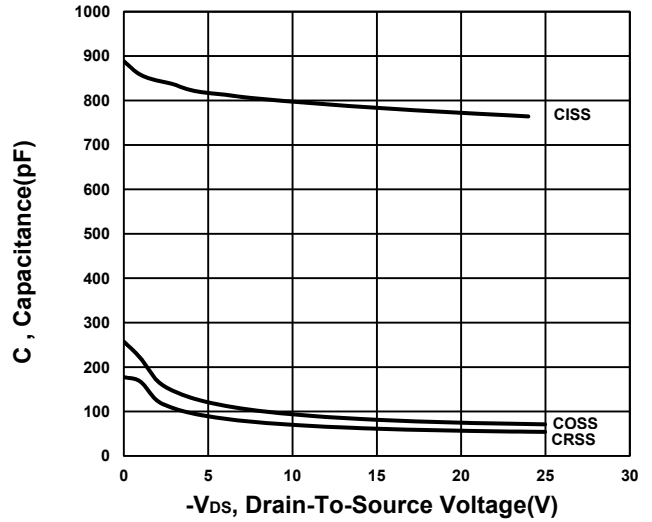
**Transfer Characteristics**



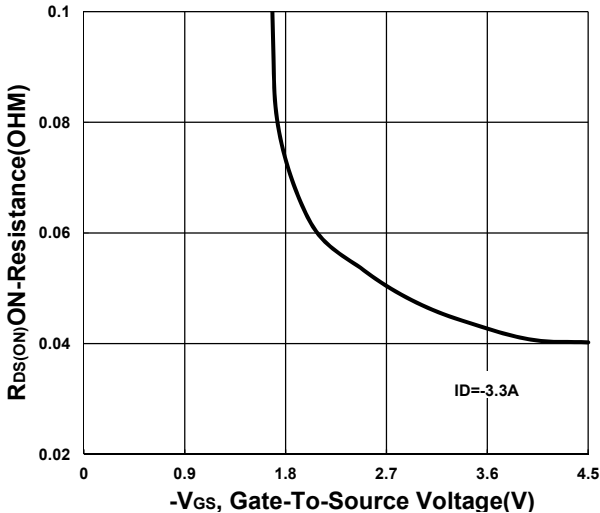
**Gate charge Characteristics**



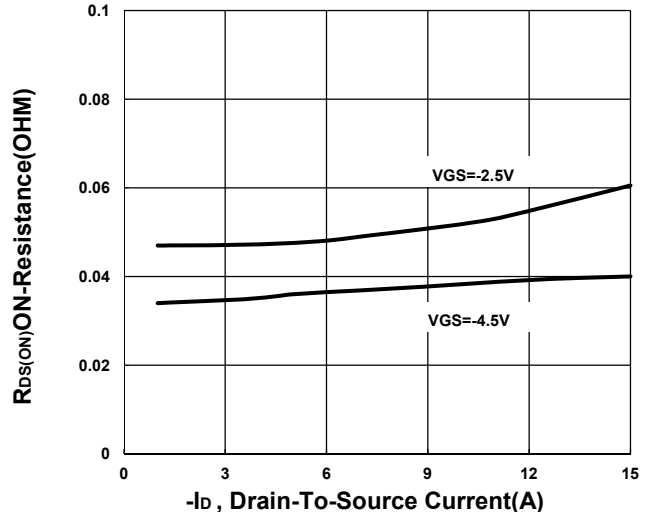
**Capacitance Characteristic**



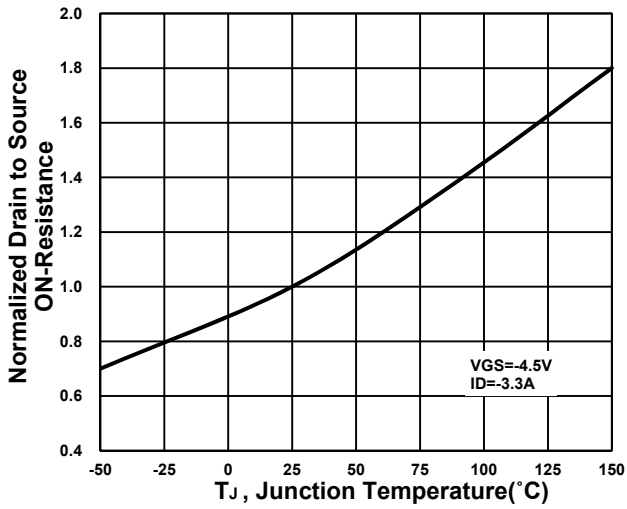
**On-Resistance VS Gate-To-Source**



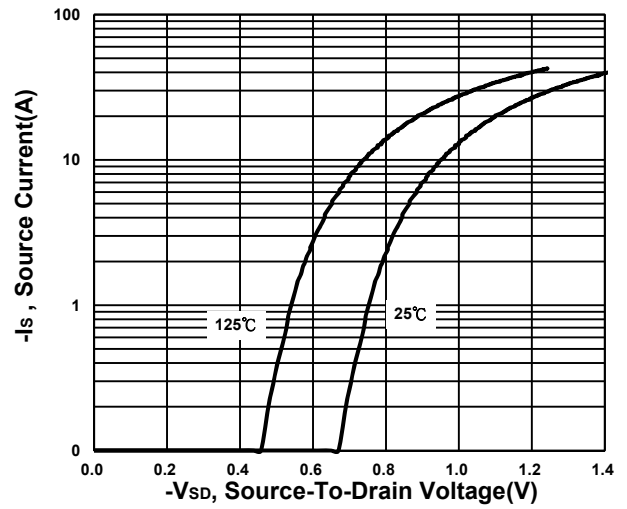
**On-Resistance VS Drain Current**



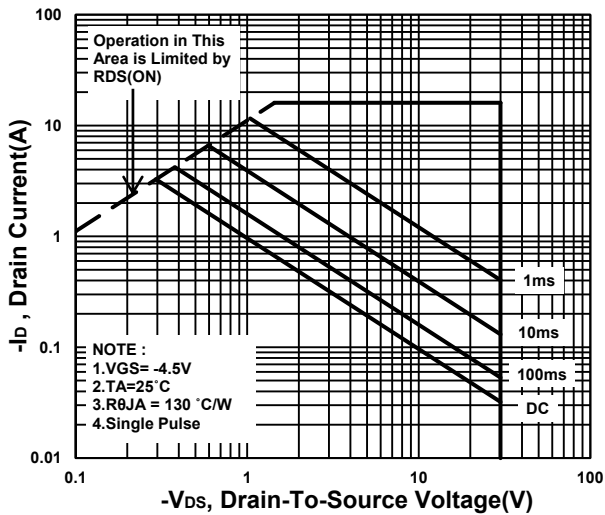
**On-Resistance VS Temperature**



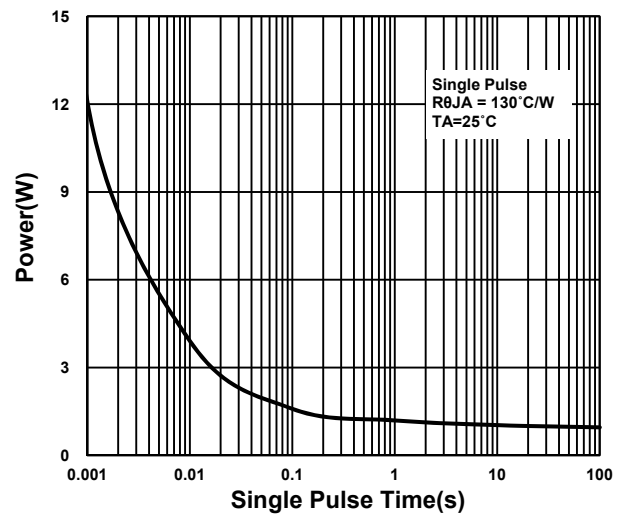
**Source-Drain Diode Forward Voltage**



**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**

